

Finland-Espoo: Miscellaneous general and special-purpose machinery
OJ S 193/2023 06/10/2023
Contract award notice
Supplies

Legal Basis:

Directive 2014/24/EU

Section I: Contracting authority

I.1. Name and addresses

Official name: VTT Technical Research Centre of Finland Ltd

National registration number: 2647375-4

Postal address: P.O. Box 1000, VTT

Town: Espoo

NUTS code: FI Suomi / Finland

Postal code: 02044

Country: Finland

E-mail: kilpailutus@vtt.fi

Telephone: +358 20722111

Internet address(es):

Main address: <https://www.vttresearch.com/en>

I.4. Type of the contracting authority

Body governed by public law

I.5. Main activity

Other activity: Research and development

Section II: Object

II.1. Scope of the procurement

II.1.1. Title

Si & Silicon oxide CMP

Reference number: 32/206/2023

II.1.2. Main CPV code

42900000 Miscellaneous general and special-purpose machinery

II.1.3. Type of contract

Supplies

II.1.4. Short description

The object of the tender is an Automatic Chemical Mechanical Polisher (later also "Equipment"), for the polishing of typical films and substrates like Si, Si-compounds, Ge and other typical wafers used in semiconductor industry of 100, 150 and 200mm diameter. The equipment shall be designed with at least two polishing platens with integrated in-situ capable pad conditioning systems, an end-point detection on at least one platen, multi-zone carrier

heads for all wafer diameters and a slurry feed system for at least 3 slurries. In addition, a supporting wafer cleaning system either integrated or stand-alone is an optional part of the tendering procedure.

The object of the tender process is described in more detail in the invitation to tender documents.

II.1.6. Information about lots

This contract is divided into lots: no

II.1.7. Total value of the procurement

Value excluding VAT: 868 626,00 EUR

II.2. Description

II.2.3. Place of performance

NUTS code: FI1B Helsinki-Uusimaa

II.2.4. Description of the procurement

The object of the tender is an Automatic Chemical Mechanical Polisher (later also "Equipment"), for the polishing of typical films and substrates like Si, Si-compounds, Ge and other typical wafers used in semiconductor industry of 100, 150 and 200mm diameter. The equipment shall be designed with at least two polishing platens with integrated in-situ capable pad conditioning systems, an end-point detection on at least one platen, multi-zone carrier heads for all wafer diameters and a slurry feed system for at least 3 slurries. In addition, a supporting wafer cleaning system either integrated or stand-alone is an optional part of the tendering procedure.

The object of the tender process is described in more detail in the invitation to tender documents.

II.2.5. Award criteria

Quality criterion - Name: Price / Weighting: 100

Price - Weighting: 100

II.2.11. Information about options

Options: yes

Description of options:

The optional parts, features and efforts which are described in more detail in the invitation to tender documents:

- Handling of 4-inch wafers (equivalent to 100mm)
- Automatic clear wafer processing capability including wafer handling on CMP system
- Standalone or integrated post CMP cleaning system with two individual dual roller PVA brush units, megasonic option and spin dry, at least 1 chemical input, and for standalone additionally: automatic cassette to cassette capability for 6 and 8 wafers with clear wafer handling capability
- 100mm membrane carrier with multi-zone (at least 3) pressure system for material removal profile control with additional independent pressure control on retainer ring
- Maintenance set for 100mm wafer carrier including at least 2 retainer rings and 3 membranes
- Multi zone pad conditioning system, with pressure control for secondary platen
- Recommended set of maintenance parts needed for smooth operation for a period of two (2) years

Offering optional parts, features and efforts are not mandatory.

II.2.13.

Information about European Union funds

The procurement is related to a project and/or programme financed by European Union funds:
yes

Identification of the project: The procurement is related to project financed by EU funds (PREVAIL=Partnership for Realization and Validation of AI hardware Leadership).

II.2.14. Additional information

Section IV: Procedure

IV.1. Description

IV.1.1. Type of procedure

Open procedure

IV.1.3. Information about a framework agreement or a dynamic purchasing system

IV.1.8. Information about the Government Procurement Agreement (GPA)

The procurement is covered by the Government Procurement Agreement: yes

IV.2. Administrative information

IV.2.1. Previous publication concerning this procedure

Notice number in the OJ S: [2023/S 097-303833](#)

IV.2.8. Information about termination of dynamic purchasing system

IV.2.9. Information about termination of call for competition in the form of a prior information notice

Section V: Award of contract

Title:

Si & Silicon oxide CMP

A contract/lot is awarded: yes

V.2. Award of contract

V.2.1. Date of conclusion of the contract

12/09/2023

V.2.2. Information about tenders

Number of tenders received: 1

Number of tenders received from SMEs: 0

Number of tenders received from tenderers from other EU Member States: 1

Number of tenders received by electronic means: 1

The contract has been awarded to a group of economic operators: no

V.2.3. Name and address of the contractor

Official name: S3-Alliance Ltd

National registration number: NI065895

Town: Derry

NUTS code: UK United Kingdom

Country: United Kingdom

The contractor is an SME: no

V.2.4. Information on value of the contract/lot

Initial estimated total value of the contract/lot: 868 626,00 EUR

Total value of the contract/lot: 868 626,00 EUR

V.2.5. Information about subcontracting

Section VI: Complementary information

VI.3. Additional information

VI.4. Procedures for review

VI.4.1. Review body

Official name: Markkinaoikeus

Postal address: Sörnäistenkatu 1

Town: Helsinki

Postal code: 00580

Country: Finland

E-mail: markkinaoikeus@oikeus.fi

Telephone: +358 295643300

Internet address: <http://www.oikeus.fi/markkinaoikeus>

VI.5. Date of dispatch of this notice

03/10/2023